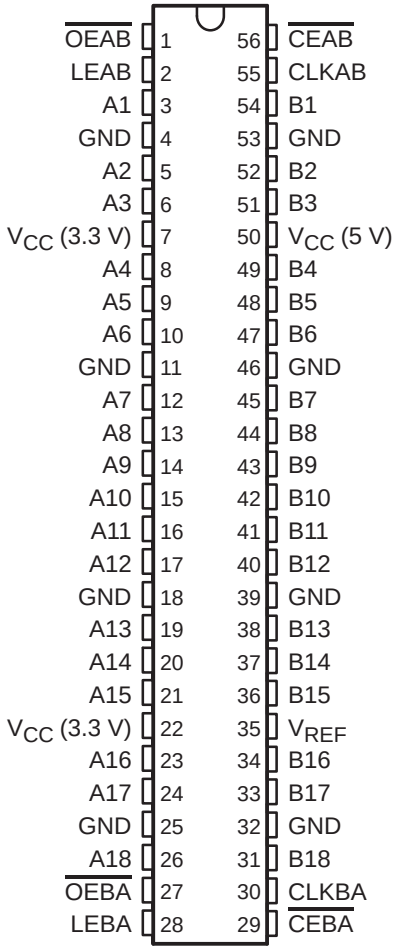
SCBS480I – JUNE 1994 – REVISED NOVEMBER 1999

- **Members of the Texas Instruments *Widebus*™ Family**
- **Universal Bus Transceiver (*UBT*™) Combines D-Type Latches and D-Type Flip-Flops for Operation in Transparent, Latched, Clocked, or Clock-Enabled Mode**
- **Translate Between GTL/GTL+ Signal Levels and LVTTL Logic Levels**
- **Support Mixed-Mode (3.3 V and 5 V) Signal Operation on A-Port and Control Inputs**
- **Identical to ’16601 Function**
- **I_{off} Supports Partial-Power-Down Mode Operation**
- **Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors on A Port**
- **Latch-Up Performance Exceeds 500 mA Per JESD 17**
- **Distributed V_{CC} and GND-Pin Configuration Minimizes High-Speed Switching Noise**
- **Package Options Include Plastic Shrink Small-Outline (DL), Thin Shrink Small-Outline (DGG), and Ceramic Flat (WD) Packages**

SN54GTL16612 . . . WD PACKAGE
SN74GTL16612 . . . DGG OR DL PACKAGE
(TOP VIEW)



description

The ’GTL16612 devices are 18-bit universal bus transceivers (UBT) that provide LVTTL-to-GTL/GTL+ and GTL/GTL+-to-LVTTL signal-level translation. They combine D-type flip-flops and D-type latches to allow for transparent, latched, clocked, and clock-enabled modes of data transfer identical to the ’16601 function. The devices provide an interface between cards operating at LVTTL logic levels and a backplane operating at GTL/GTL+ signal levels. Higher-speed operation is a direct result of the reduced output swing (<1 V), reduced input threshold levels, and output edge control (OEC™).

The user has the flexibility of using these devices at either GTL (V_{TT} = 1.2 V and V_{REF} = 0.8 V) or the preferred higher noise margin GTL+ (V_{TT} = 1.5 V and V_{REF} = 1 V) signal levels. GTL+ is the Texas Instruments derivative of the Gunning transceiver logic (GTL) JEDEC standard JESD 8-3. The B port normally operates at GTL or GTL+ signal levels, while the A-port and control inputs are compatible with LVTTL logic levels and are 5-V tolerant. V_{REF} is the reference input voltage for the B port.

V_{CC} (5 V) supplies the internal and GTL circuitry while V_{CC} (3.3 V) supplies the LVTTL output buffers.

description (continued)

Data flow in each direction is controlled by output-enable ($\overline{OEAB}$ and $\overline{OEBA}$), latch-enable(LEAB and LEBA), and clock (CLKAB and CLKBA) inputs. The clock can be controlled by the clock-enable ($\overline{CEAB}$ and $\overline{CEBA}$) inputs. For A-to-B data flow, the devices operate in the transparent mode when LEAB is high. When LEAB is low, the A data is latched if $\overline{CEAB}$ is low and CLKAB is held at a high or low logic level. If LEAB is low, the A data is stored in the latch/flip-flop on the low-to-high transition of CLKAB if $\overline{CEAB}$ also is low. When $\overline{OEAB}$ is low, the outputs are active. When $\overline{OEAB}$ is high, the outputs are in the high-impedance state. Data flow for B to A is similar to that for A to B, but uses $\overline{OEBA}$, LEBA, CLKBA, and $\overline{CEBA}$.

These devices are fully specified for partial-power-down applications using I_{off}. The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

Active bus-hold circuitry holds unused or undriven LVTTL inputs at a valid logic state. Use of pullup or pulldown resistors with the bus-hold circuitry is not recommended.

The SN54GTL16612 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN74GTL16612 is characterized for operation from –40°C to 85°C.

FUNCTION TABLE†

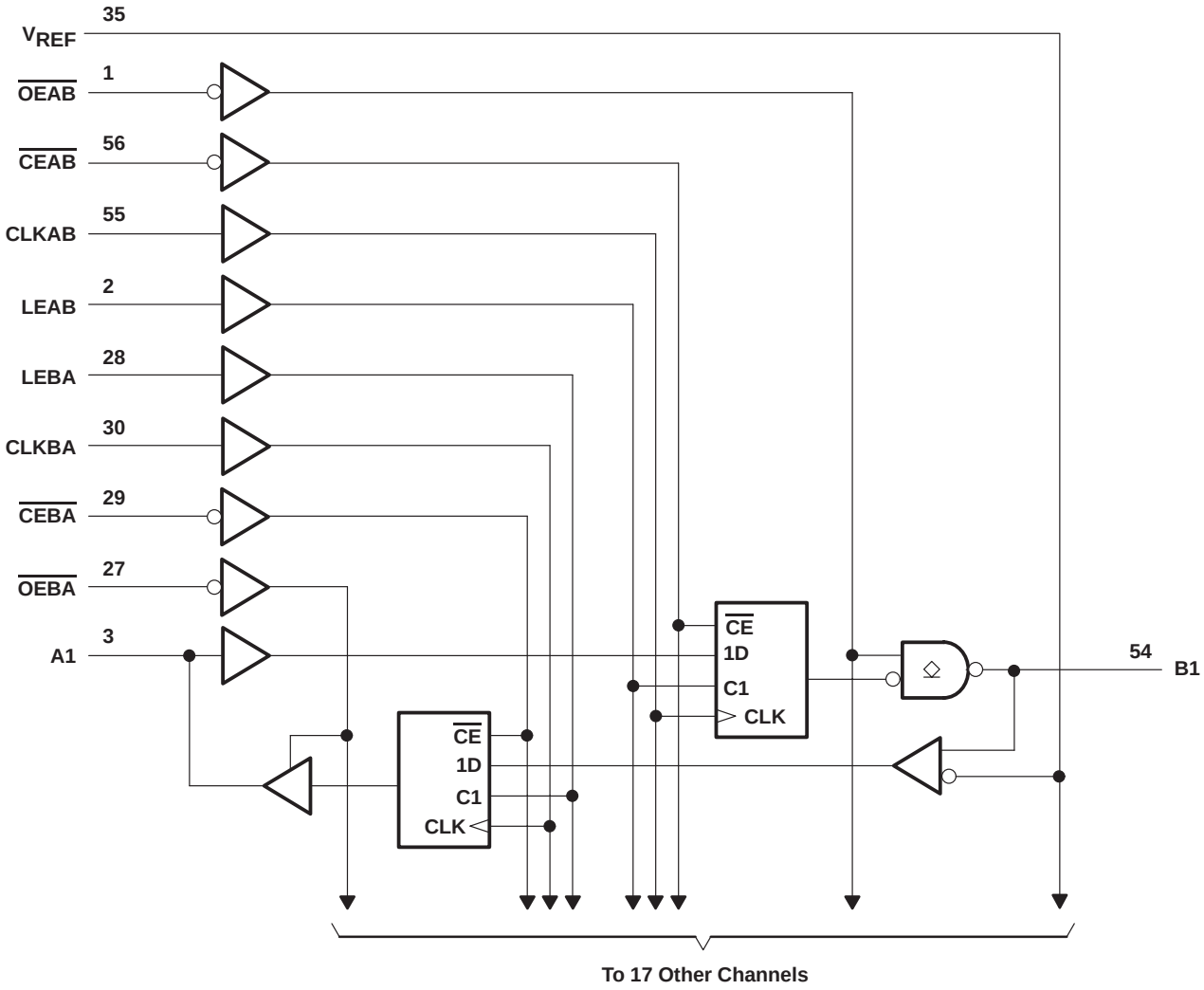
INPUTS					OUTPUT B	MODE
$\overline{CEAB}$	$\overline{OEAB}$	LEAB	CLKAB	A		
X	H	X	X	X	Z	Isolation
L	L	L	H	X	B_0‡	Latched storage of A data
L	L	L	L	X	B_0§	
X	L	H	X	L	L	Transparent
X	L	H	X	H	H	
L	L	L	↑	L	L	Clocked storage of A data
L	L	L	↑	H	H	
H	L	L	X	X	B_0§	Clock inhibit

† A-to-B data flow is shown. B-to-A data flow is similar but uses $\overline{OEBA}$, LEBA, CLKBA, and $\overline{CEBA}$.

‡ Output level before the indicated steady-state input conditions were established, provided that CLKAB was high before LEAB went low

§ Output level before the indicated steady-state input conditions were established

logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC}: 3.3 V . . . . . –0.5 V to 4.6 V
5 V . . . . . –0.5 V to 7 V
Input voltage range, V_I (see Note 1): A-port and control inputs . . . . . –0.5 V to 7 V
B port and V_{REF} . . . . . –0.5 V to 4.6 V
Voltage range applied to any output in the high or power-off state, V_O
(see Note 1): A port . . . . . –0.5 V to 7 V
B port . . . . . –0.5 V to 4.6 V
Current into any output in the low state, I_O: A port . . . . . 128 mA
B port . . . . . 80 mA
Current into any A-port output in the high state, I_O (see Note 2) . . . . . 64 mA
Continuous current through each V_{CC} or GND . . . . . ±100 mA
Input clamp current, I_{IK} ($V_I < 0$) . . . . . –50 mA
Output clamp current, I_{OK} ($V_O < 0$) . . . . . –50 mA
Package thermal impedance, θ_{JA} (see Note 3): DGG package . . . . . 64°C/W
DL package . . . . . 56°C/W
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
2. This current flows only when the output is in the high state and $V_O > V_{CC}$.
3. The package thermal impedance is calculated in accordance with JESD 51.

recommended operating conditions (see Notes 4 through 6)

			SN54GTL16612			SN74GTL16612			UNIT
			MIN	NOM	MAX	MIN	NOM	MAX	
V_{CC}	Supply voltage	3.3 V	3.15	3.3	3.45	3.15	3.3	3.45	V
		5 V	4.75	5	5.25	4.75	5	5.25	
V_{TT}	Termination voltage	GTL	1.14	1.2	1.26	1.14	1.2	1.26	V
		GTL+	1.35	1.5	1.65	1.35	1.5	1.65	
V_{REF}	Supply voltage	GTL	0.74	0.8	0.87	0.74	0.8	0.87	V
		GTL+	0.87	1	1.1	0.87	1	1.1	
V_I	Input voltage	B port			V_{TT}			V_{TT}	V
		Except B port			5.5			5.5	
V_{IH}	High-level input voltage	B port	V_{REF}+50 mV			V_{REF}+50 mV			V
		Except B port	2			2			
V_{IL}	Low-level input voltage	B port			V_{REF}–50 mV			V_{REF}–50 mV	V
		Except B port			0.8			0.8	
I_{IK}	Input clamp current				–18			–18	mA
I_{OH}	High-level output current	A port			–32			–32	mA
I_{OL}	Low-level output current	A port			64			64	mA
		B port			40			40	
T_A	Operating free-air temperature		–55		125	–40		85	°C

NOTES: 4. All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
5. Normal connection sequence is GND first, V_{CC} = 5 V second, and V_{CC} = 3.3 V, I/O, control inputs, V_{TT} and V_{REF} (any order) last.
6. V_{TT} and R_{TT} can be adjusted to accommodate backplane impedances as long as they do not exceed the DC absolute I_{OL} ratings. Similarly, V_{REF} can be adjusted to optimize noise margins, but normally is 2/3 V_{TT}.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS		SN54GTL16612			SN74GTL16612			UNIT
				MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{IK}		V_{CC} (3.3 V) = 3.15 V, V_{CC} (5 V) = 4.75 V	I_I = –18 mA			–1.2			–1.2	V
V_{OH}	A port	V_{CC} (3.3 V)= 3.15 V to 3.45 V, V_{CC} (5 V) = 4.75 V to 5.25 V	I_{OH} = –100 µA	V_{CC} (3.3 V)–0.2			V_{CC} (3.3 V)–0.2			V
		V_{CC} (3.3 V) = 3.15 V, V_{CC} (5 V) = 4.75 V	I_{OH} = –8 mA	2.4			2.4			
			I_{OH} = –32 mA	2			2			
V_{OL}	A port	V_{CC} (3.3 V) = 3.15 V, V_{CC} (5 V) = 4.75 V	I_{OL} = 100 µA			0.2			0.2	V
			I_{OL} = 16 mA			0.4			0.4	
			I_{OL} = 32 mA			0.5			0.5	
			I_{OL} = 64 mA			0.6			0.55	
	B port	V_{CC} (3.3 V) = 3.15 V, V_{CC} (5 V) = 4.75 V, I_{OL} = 40 mA				0.5			0.4	
I_I	Control inputs	V_{CC} (3.3 V) = 0 or 3.45 V, V_{CC} (5 V) = 0 or 5.25 V	V_I = 5.5 V			10			10	µA
	A port	V_{CC} (3.3 V) = 3.45 V, V_{CC} (5 V) = 5.25 V	V_I = 5.5 V			1000			20	
			V_I = V_{CC} (3.3 V)			1			1	
			V_I = 0			–30			–30	
	B port	V_{CC} (3.3 V) = 3.45 V, V_{CC} (5 V) = 5.25 V	V_I = V_{CC} (3.3 V)			5			5	
			V_I = 0			–5			–5	
I_{off}		V_{CC} = 0,	V_I or V_O = 0 to 4.5 V			1000			100	µA
$I_{I(hold)}$	A port	V_{CC} (3.3 V) = 3.15 V, V_{CC} (5 V) = 4.75 V	V_I = 0.8 V	75			75			µA
			V_I = 2 V	–75			–75			
			V_I = 0 to V_{CC} (3.3 V)‡			±500			±500	
I_{OZH}	A port	V_{CC} (3.3 V) = 3.45 V, V_{CC} (5 V) = 5.25 V, V_O = 3 V				1			1	µA
	B port	V_{CC} (3.3 V) = 3.45 V, V_{CC} (5 V) = 5.25 V, V_O = 1.2 V				10			10	
I_{OZL}	A port	V_{CC} (3.3 V) = 3.45 V, V_{CC} (5 V) = 5.25 V, V_O = 0.5 V				–1			–1	µA
	B port	V_{CC} (3.3 V) = 3.45 V, V_{CC} (5 V) = 5.25 V, V_O = 0.4 V				–10			–10	
I_{CC} (3.3 V)	A or B port	V_{CC} (3.3 V) = 3.45 V, V_{CC} (5 V) = 5.25 V, I_O = 0, V_I = V_{CC} (3.3 V) or GND	Outputs high			1			1	mA
			Outputs low			5			5	
			Outputs disabled			1			1	
I_{CC} (5 V)	A or B port	V_{CC} (3.3 V) = 3.45 V, V_{CC} (5 V) = 5.25 V, I_O = 0, V_I = V_{CC} (3.3 V) or GND	Outputs high			120			120	mA
			Outputs low			120			120	
			Outputs disabled			120			120	
ΔI_{CC}§		V_{CC} (3.3 V) = 3.45 V, V_{CC} (5 V) = 5.25 V, A-port or control inputs at V_{CC} (3.3 V) or GND, One input at 2.7 V				1			1	mA
C_i	Control inputs	V_I = 3.15 V or 0			3.5	12		3.5		pF
C_{io}	A port	V_O = 3.15 V or 0			12	18		12		pF
	B port					10			5	

† All typical values are at V_{CC} (3.3 V) = 3.3 V, V_{CC} (5 V) = 5 V, T_A = 25°C.
‡ This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.
§ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V_{CC} or GND.

timing requirements over recommended ranges of supply voltage and operating free-air temperature, V_{TT} = 1.2 V and V_{REF} = 0.8 V for GTL (unless otherwise noted) (see Figure 1)

			SN54GTL16612		SN74GTL16612		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	95	0	95	MHz
t_w	Pulse duration	LEAB or LEBA high	3.3		3.3		ns
		CLKAB or CLKBA high or low	5.6		5.6		
t_{su}	Setup time	A before CLKAB↑	1.3		1.3		ns
		B before CLKBA↑	3.4		2.5		
		A before LEAB↓	1.2		0		
		B before LEBA↓	1		1		
		$\overline{CEAB}$ before CLKAB↑	2.1		2		
		$\overline{CEBA}$ before CLKBA↑	2.6		2.2		
t_h	Hold time	A after CLKAB↑	2.9		1.6		ns
		B after CLKBA↑	4.1		0.3		
		A after LEAB↓	4.5		4		
		B after LEBA↓	4.3		3.6		
		$\overline{CEAB}$ after CLKAB↑	2		0.8		
		$\overline{CEBA}$ after CLKBA↑	1.1		1.1		

switching characteristics over recommended ranges of supply voltage and operating free-air temperature, V_{TT} = 1.2 V and V_{REF} = 0.8 V for GTL (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54GTL16612			SN74GTL16612			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
f_{max}			95			95			MHz
t_{PLH}	A	B	1	2.8	4.5	1.5	2.8	4.1	ns
t_{PHL}			1	2.5	4.5	1.3	2.5	4	
t_{PLH}	LEAB	B	1	3.6	5.5	2	3.6	5.3	ns
t_{PHL}			1	3.5	6	1.9	3.5	5.4	
t_{PLH}	CLKAB	B	1	3.7	5.5	2.3	3.7	5.3	ns
t_{PHL}			1	3.4	5.5	1.9	3.4	5.4	
t_{en}	$\overline{OEAB}$	B	1	3.3	5.5	2	3.3	5.5	ns
t_{dis}			1	3.4	5.5	2	3.4	5.1	
t_r	Transition time, B outputs (0.5 V to 1 V)			1.3			1.3		ns
t_f	Transition time, B outputs (1 V to 0.5 V)			0.5			0.5		ns
t_{PLH}	B	A	2	4.1	6.9	2.1	4.1	6.3	ns
t_{PHL}			1	2.9	5.1	1.2	2.9	4.6	
t_{PLH}	LEBA	A	2	3.7	6.1	2.3	3.7	5.7	ns
t_{PHL}			1	3	5.1	1.8	3	4.8	
t_{PLH}	CLKBA	A	2	3.8	6.4	2.5	3.8	6.1	ns
t_{PHL}			2	3.3	5.6	2.3	3.3	5.2	
t_{en}	$\overline{OEBA}$	A	1	5	7.5	2.3	5	7.4	ns
t_{dis}			2	4.3	6.9	2.5	4.3	6.4	

† All typical values are at V_{CC} (3.3 V) = 3.3 V, V_{CC} (5 V) = 5 V, T_A = 25°C.

timing requirements over recommended ranges of supply voltage and operating free-air temperature, V_{TT} = 1.5 V and V_{REF} = 1 V for GTL+ (unless otherwise noted) (see Figure 1)

			SN54GTL16612		SN74GTL16612		UNIT
			MIN	MAX	MIN	MAX	
f_{clock}	Clock frequency		0	95	0	95	MHz
t_w	Pulse duration	LEAB or LEBA high	3.3		3.3		ns
		CLKAB or CLKBA high or low	5.6		5.6		
t_{su}	Setup time	A before CLKAB↑	1.3		1.3		ns
		B before CLKBA↑	3.2		2.3		
		A before LEAB↓	1.2		0		
		B before LEBA↓	1.3		1.3		
		$\overline{CEAB}$ before CLKAB↑	2.1		2		
		$\overline{CEBA}$ before CLKBA↑	2.6		2.2		
t_h	Hold time	A after CLKAB↑	2.9		1.6		ns
		B after CLKBA↑	4.4		0.3		
		A after LEAB↓	4.5		4		
		B after LEBA↓	4.3		3.6		
		$\overline{CEAB}$ after CLKAB↑	2		0.8		
		$\overline{CEBA}$ after CLKBA↑	1.1		1.1		

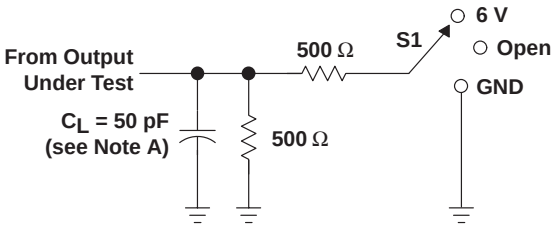
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, V_{TT} = 1.5 V and V_{REF} = 1 V for GTL+ (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	SN54GTL16612			SN74GTL16612			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
f_{max}			95			95			MHz
t_{PLH}	A	B	1	2.8	4.5	1.5	2.8	4.1	ns
t_{PHL}			1	2.5	4.6	1.3	2.5	4.1	
t_{PLH}	LEAB	B	1	3.6	5.5	2	3.6	5.3	ns
t_{PHL}			1	3.5	6.1	1.9	3.5	5.5	
t_{PLH}	CLKAB	B	1	3.7	5.5	2.3	3.7	5.3	ns
t_{PHL}			1	3.4	5.6	1.9	3.4	5.5	
t_{PLH}	$\overline{OEAB}$	B	1	3.4	5.5	2	3.4	5.1	ns
t_{PHL}			1	3.3	5.6	2	3.3	5.6	
t_r	Transition time, B outputs (0.5 V to 1 V)			1.5			1.5		ns
t_f	Transition time, B outputs (1 V to 0.5 V)			0.8			0.8		ns
t_{PLH}	B	A	1.9	4	6.9	2	4	6.3	ns
t_{PHL}			0.9	2.8	4.9	1.1	2.8	4.4	
t_{PLH}	LEBA	A	2	3.7	6.1	2.3	3.7	5.7	ns
t_{PHL}			1	3	5.1	1.8	3	4.8	
t_{PLH}	CLKBA	A	2	3.8	6.4	2.5	3.8	6.1	ns
t_{PHL}			2	3.3	5.6	2.3	3.3	5.2	
t_{en}	OEBA	A	1	5	7.5	2.3	5	7.4	ns
t_{dis}			2	4.3	6.9	2.5	4.3	6.4	

† All typical values are at V_{CC} (3.3 V) = 3.3 V, V_{CC} (5 V) = 5 V, T_A = 25°C.

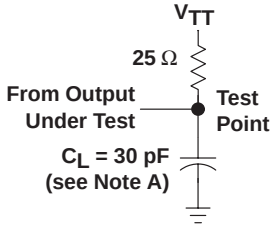
PARAMETER MEASUREMENT INFORMATION

V_{TT} = 1.2 V , V_{REF} = 0.8 V FOR GTL AND V_{TT} = 1.5 V , V_{REF} = 1 V FOR GTL+

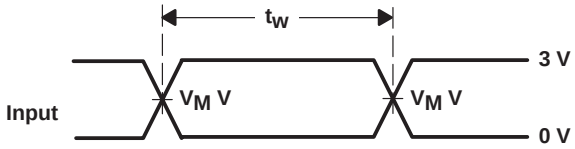


TEST	S1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	6 V
t_{PHZ}/t_{PZH}	GND

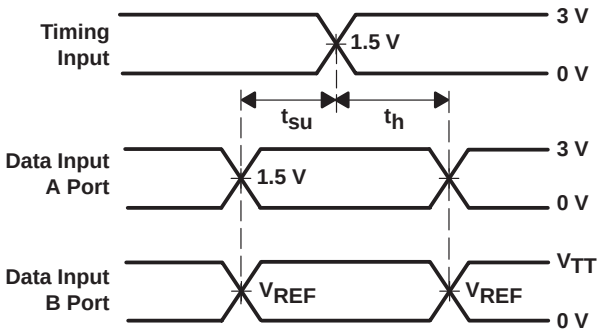
LOAD CIRCUIT FOR A OUTPUTS



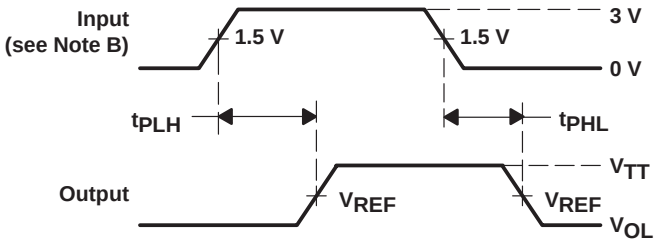
LOAD CIRCUIT FOR B OUTPUTS



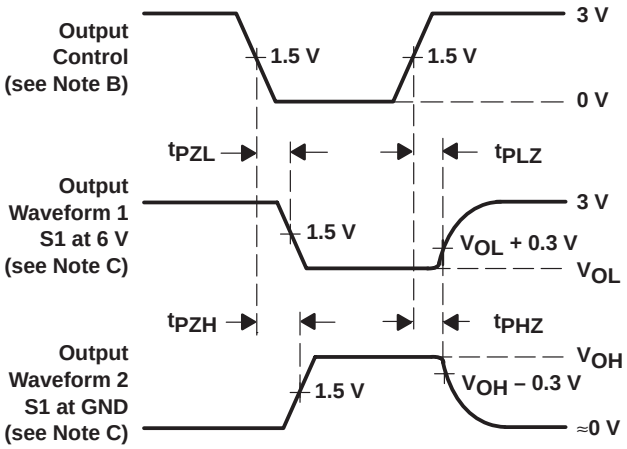
VOLTAGE WAVEFORMS
PULSE DURATION
(V_M = 1.5 V for A port and V_{REF} for B port)†



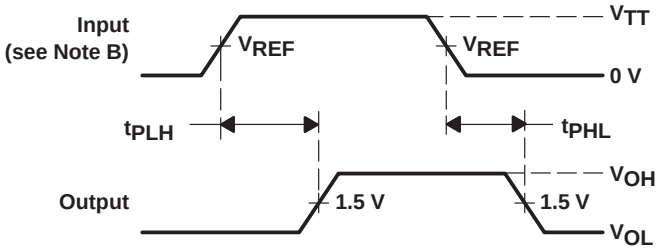
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
(A port to B port)†



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
(A port)



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
(B port to A port)†

† All control inputs are TTL levels

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, Z_O = 50 Ω, t_r ≤ 2.5 ns, t_f ≤ 2.5 ns.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuits and Voltage Waveform

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